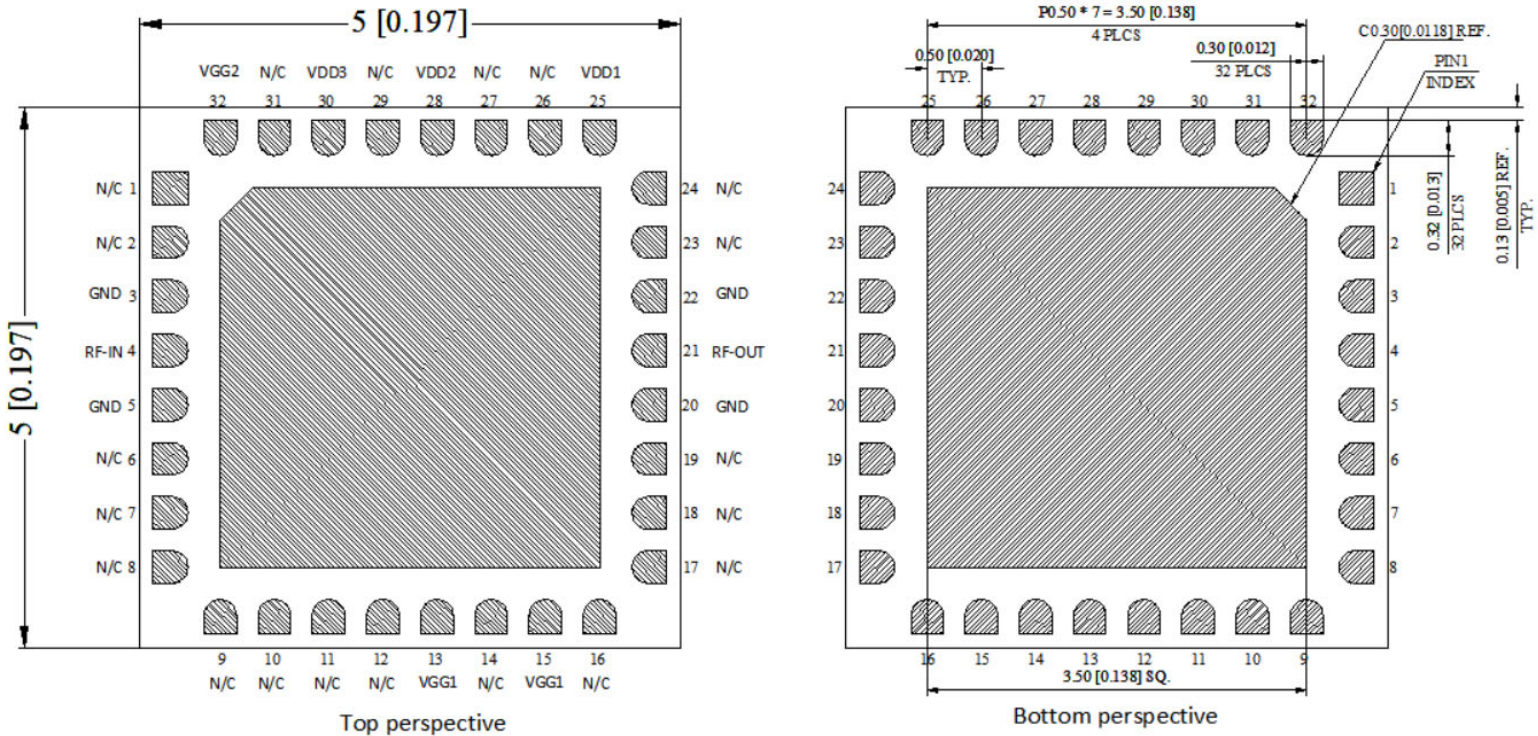

Dimensions and pin description:

Notes:

1. Pad Plating Ni:1.27-8.89um Au: 0.3um Min
2. Dimensions shown in mm[inch].

Pin Descriptions

Pin Number	Function	Description
6	RF-IN	This pad is DC coupled and matched to 50 Ohms
21	RF-OUT	RF output for amplifier
14	VG1	Amplifier 1st gate bias; connect to external 1000pF and 0.01uF bypass capacitors.
32	VG2	Amplifier 1st gate bias; connect to external 1000pF and 0.01uF bypass capacitors.
15	EXT1	External bypass pad; connect to external 0.47uF bypass capacitor.
16	EXT2	External bypass pad; connect to external 1000pF bypass capacitor.
31	EXT3	External bypass pad; connect to external 1000pF bypass capacitor.
30	EXT4	External bypass pad; connect to external 0.47uF bypass capacitor.
5,7,13,20,22,29	GND	Ground pad
Die Bottom	GND	Die bottom must be connected to RF/DC ground

Recommended lead-free reflow temperature curve:

